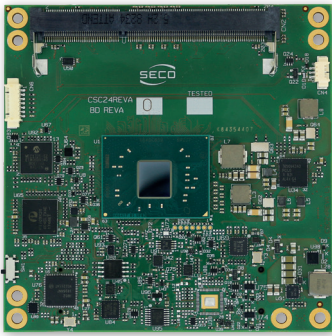




## COMe-C24-CT6 COM Express™ 3.0 Compact Type 6 Module with the Intel® Atom™ X Series, Intel® Celeron® J / N Series and Intel® Pentium® N Series (formerly Apollo Lake) Processors

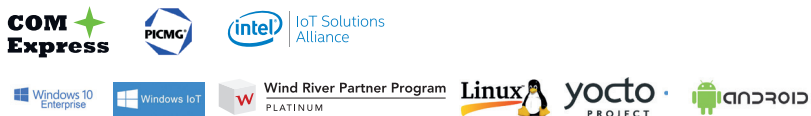
Rugged solution for industrial environment



### HIGHLIGHTS

<b>CPU</b> Intel® Atom™ X Series, Intel® Celeron® J / N Series and Intel® Pentium® N Series (formerly Apollo Lake) Processors	<b>CONNECTIVITY</b> 4x USB 3.0; 8x USB 2.0; 5x PCI-e x1 Gen2
<b>GRAPHICS</b> Intel® HD Graphics 500 series controller with up to 18 Execution Units	<b>MEMORY</b> Two DDR3L SO-DIMM Slots supporting DDR3L-1866 non-ECC Memory

Available in Industrial Temperature Range



DEVELOPMENT | SAMPLING | PRODUCTION

### MAIN FIELDS OF APPLICATION



### FEATURES

<b>Processor</b> Intel® Atom™ <b>x5-E3930</b> Dual Core @1.3 GHz (Burst 1.8GHz), 2MB L2 Cache, 6.5W TDP Intel® Atom™ <b>x5-E3940</b> Quad Core @1.6 GHz (Burst 1.8GHz), 2MB L2 Cache, 9.5W TDP Intel® Atom™ <b>x7-E3950</b> Quad Core @1.6 GHz (Burst 2.0GHz), 2MB L2 Cache, 12W TDP Intel® Pentium® <b>N4200</b> Quad Core @1.1GHz (Burst 2.5GHz), 2MB L2 Cache, 6W TDP Intel® Celeron® <b>N3350</b> Dual Core @1.1GHz (Burst 2.4GHz), 2MB L2 Cache, 6W TDP Intel® Celeron® <b>J3455</b> , Quad Core @1.5GHz (Burst 2.3GHz), 2MB L2Cache, 10W TDP Intel® Celeron® <b>J3355</b> , Dual Core @2.0GHz (Burst 2.5GHz), 2MB L2Cache, 10W TDP	<b>Mass Storage</b> Optional eMMC 5.0 drive soldered on-board 2 x external S-ATA Gen3 Channels microSD Card Slot on-board
<b>Max Cores</b> 4	<b>Networking</b> Optional Gigabit Ethernet interface Intel® I210 or I211 GbE Controller (MAC + PHY)
<b>Max Thread</b> 4	<b>USB</b> Up to 4 x USB 3.0 Host ports 8 x USB 2.0 Host ports
<b>Memory</b> Two DDR3L SO-DIMM Slots supporting DDR3L-1866 non-ECC Memory, up to 8GB	<b>PCI-e</b> Up to 5 x PCI-e x 1 Gen2 lanes
<b>Graphics</b> Integrated Intel® HD Graphics 500 series controller with up to 18 Execution Units Three Independent displays supported HW decoding of HEVC(H.265), H.264, MVC, VP8, VP9, MPEG2, VC-1, WMV9, JPEG/MJPEG formats HW encoding of HEVC(H.265), H.264, MVC, VP8, VP9 and JPEG/MPEG formats	<b>Audio</b> HD Audio Interface
<b>Video Interfaces</b> Up to 2 x Digital Display Interfaces (DDIs), supporting DP 1.2, DVI and HDMI 1.4b eDP 1.3 or Single/Dual-Channel 18-/24-bit LVDS interface optional VGA interface through a DP-to-VGA bridge	<b>Serial Ports</b> 2x UARTs
<b>Video Resolution</b> DP: Up to 4096 x 2160 @60HZ eDP: Up to 3840 x 2160 @60HZ HDMI: Up to 3840 x 2160 @30HZ LVDS, VGA: Up to 1920 x 1200 @ 60HZ	<b>Other Interfaces</b> SPI, I2C, SM Bus, Thermal Management, FAN management LPC bus Optional TPM 2.0 on-board LID#/SLEEP#/PWRBTN#, Watchdog 4x GPI, 4 x GPO
	<b>Power Supply</b> +12V <sub>DC</sub> ± 10% and +5V <sub>SB</sub> (optional)
	<b>Operating System</b> Microsoft® Windows 10 Enterprise (64-bit) Microsoft® Windows 10 IoT core Wind River Linux (64 bit) Yocto (64 bit) Android (planning)
	<b>Operating Temperature*</b> 0°C ÷ +60°C (Commercial version) -40°C ÷ +85°C (Industrial version)
	<b>Dimensions</b> 95 x 95 mm (Com Express™ Compact Form factor, Type 6 pinout)

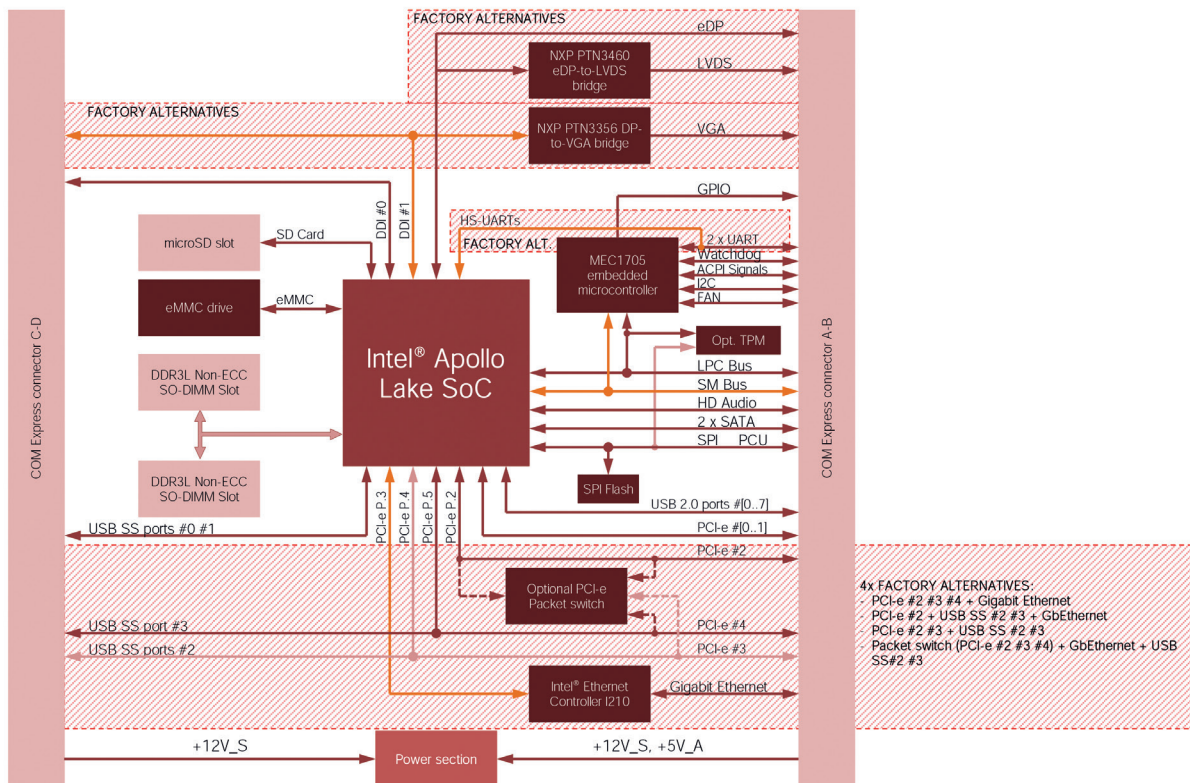
\*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.



# COMe-C24-CT6

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## BLOCK DIAGRAM



Information subject to change. Please visit [www.seco.com](http://www.seco.com) to find the latest version of this datasheet.

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